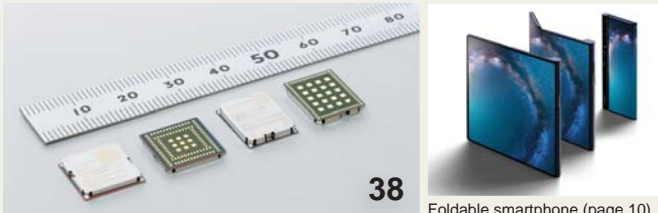




39



38

Foldable smartphone (page 10)

DEPARTMENTS

-  AEI NEWS **08**
-  IN VIEW THIS MONTH **10**
-  COMPANY ON THE MOVE **51**
-  PRODUCT NEWS **57**

ASIA ELECTRONICS INDUSTRY (ISSN 1342-422X) is published monthly by Dempa Publications, Inc., 1-11-15 Higashi Gotanda, Shinagawa-ku, Tokyo 141-8715, Japan Tel: +81-3-3445-6111 Fax: +81-3-3445-6890. Editorial e-mail: may@dempa.co.jp;

Subscription e-mail: circulationmanila@dempa.co.jp. The magazine is distributed free to qualified subscribers in ASEAN countries (Thailand, Indonesia, The Philippines, Malaysia, Singapore, Brunei, Vietnam, Myanmar, Cambodia and Laos), as well as Korea, Taiwan and Hong Kong.

Paid air mail subscription is available to non-qualified subscribers in the Asian and Pacific regions for US\$150 per year and US\$260 for two years. For other areas, air mail subscription fees are US\$160 per year and US\$280 for two years. Paid subscription is accepted at <https://www.dempa.co.jp/en/pdfs/orderform.pdf>

Send address corrections to Dempa Publications, Inc., c/o Quantum Solutions (HK) Ltd. Unit 3-6, G/F Pacific Trade Centre, 2 Kai Hing Road, Kowloon Bay, Kowloon, Hong Kong

TAIWAN: International Dempa Trade Co. Ltd., 7F, No. 34, Sec. 1, Nanjing East Road., Taipei, Taiwan 104 Tel: +886-2-2563 4595 Fax: +886-2-2567-5559 **KOREA:** Dempa Publications, Room 1019, Punglim VIP Tel, 404, Gongdeuk-dong, Mapo, Seoul, Korea 04144, Tel: +82-2-714-2983 Fax: +82-2-714-2984 **PHILIPPINES:** Dempa Publications, Inc. - Regional Headquarters, Herrera Tower, Room 2510, 98 V.A. Rufino Street, Salcedo Village, Makati City, Philippines, Tel: +63-2-845-0906 Fax: +63-2-845-1829

President & Publisher: Tsutomu Hirayama
Copyright © 2019 by Dempa Publications, Inc.

All rights reserved. The contents of this magazine may not be reproduced in whole or in part without the prior permission of the copyright owner. Printed in China.

SPECIAL REPORT

- SMDs Sustain Miniaturization, High-Density Packaging Track** _____ **11**
- NXP Raises Automotive Security to New Heights** _____ **13**

TECH FOCUS

- JAE Expands Features of USB Type-C Connectors** _____ **16**
- Hirose Electric Pursues Connector Technologies for 4K/8K Video Equipment** _____ **18**
- Thin-Film Alloy Magnets Turn into Flexible Sensor** _____ **20**
- Memory Chip Technologies Evolve with Deluge of Data** _____ **22**

COMPONENT MATERIALS _____ **23**

SMTs: IN REVIEW _____ **25**

TEST AND MEASUREMENT _____ **29**

MOBILITY _____ **31**

TECHNOLOGY HIGHLIGHT

- Stacked CMOS Image Sensor Magnifies Imaging, Miniaturization** _____ **35**

PRODUCT HIGHLIGHT

- PAM 4-Compliant Bridge Chip Bolsters SSD Speed, Capacity** _____ **37**
- Smallest LPWA Modules Halve Size of Conventional Modules** _____ **38**
- JAE Expands Connector Lineup for Automotives** _____ **38**

SHOW REPORT

- electronica & productronica China and SEMICON China 2019** _____ **39**
- Converting Technology Exhibition 2019** _____ **48**

TOP INTERVIEW

- Nihon Denkei Strengthens Capability in Automotive Test Service** _____ **50**

MANUFACTURING FRONT

- Nichicon to Install Second Fully Automated Line in China** _____ **52**

INDUSTRY REPORT

- Connector Technologies Hinge on New Car Trends** _____ **53**
- Toyo Keisokuki Provides Venue for International Exchange** _____ **54**

ZOOM-IN _____ **55**